

Xinger®

Ultra Low Profile 0805 Balun 50Ω to 200Ω Balanced



Description

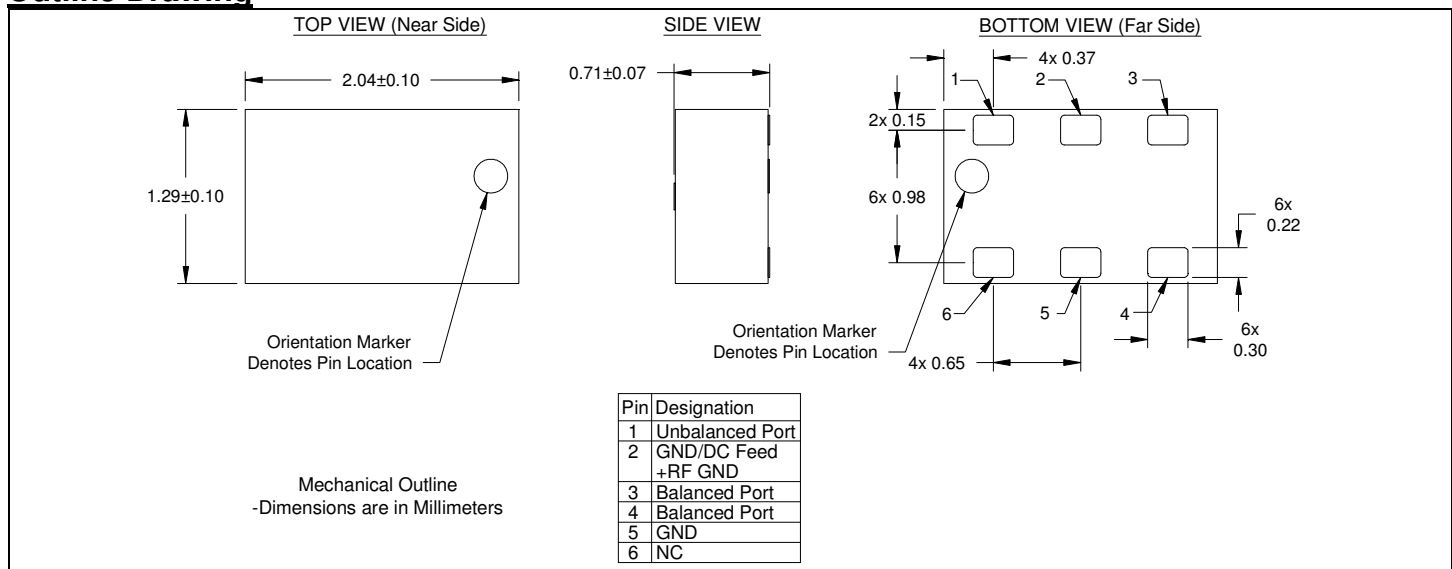
The BD3438J50200AHF is a low profile sub-miniature balanced to unbalanced transformer designed for differential inputs and output locations on modern chipsets in an easy to use surface mount package. The BD3438J50200AHF is ideal for high volume manufacturing and is higher performance than traditional ceramic and lumped element baluns. The BD3438J50200AHF has an unbalanced port impedance of 50Ω and a 200Ω balanced port impedance. This transformation enables single ended signals to be applied to differential ports on modern semiconductors. The output ports have equal amplitude (-3dB) with 180 degree phase differential. The BD3438J50200AHF is available on tape and reel for pick and place high volume manufacturing.

Detailed Electrical Specifications: Specifications subject to change without notice.

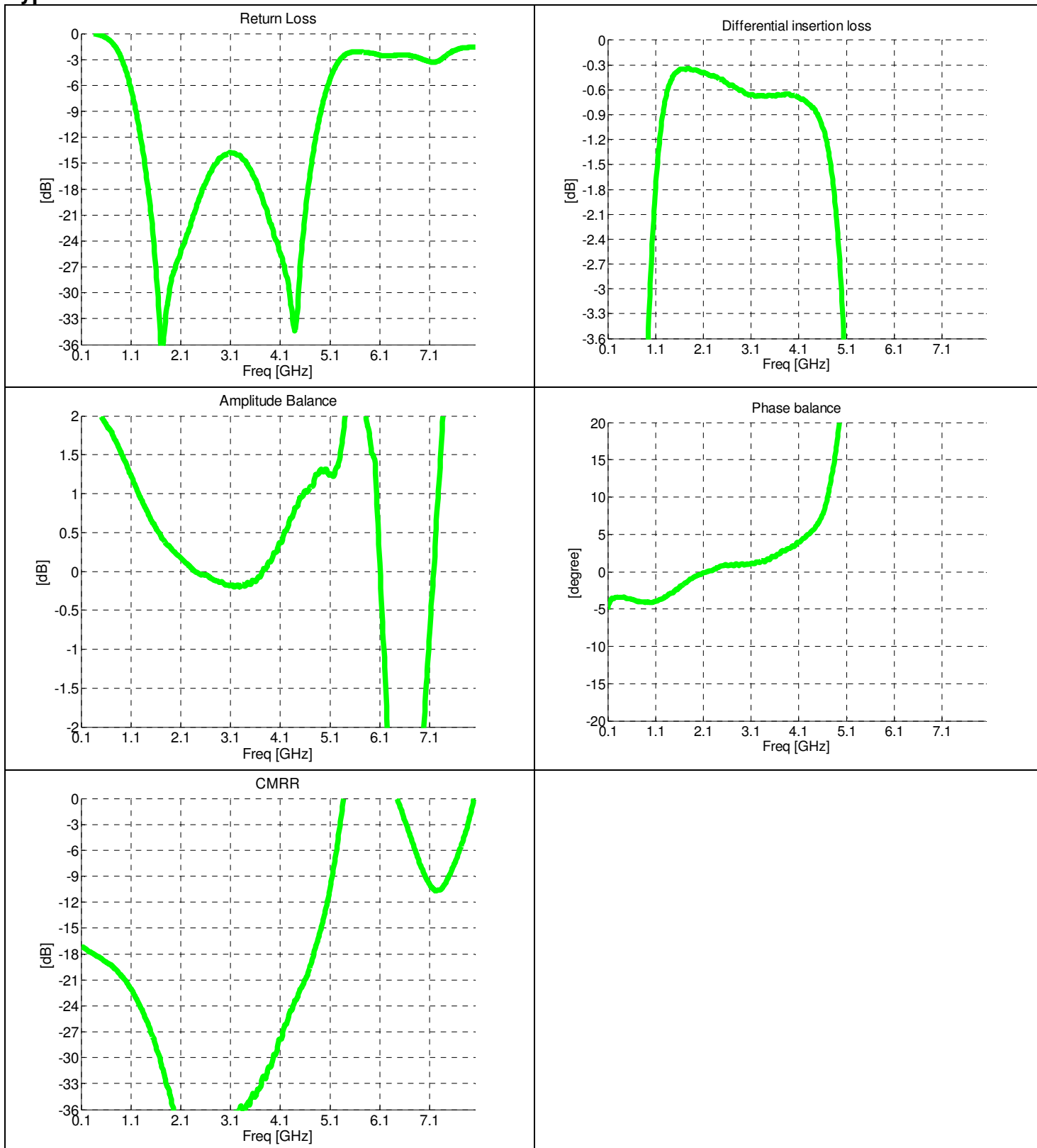
Features:	Parameter	ROOM (25°C)			Unit
		Min.	Typ.	Max	
<ul style="list-style-type: none"> • 3400 – 3800 MHz • 0.7mm Height Profile • 50 Ohm to 2 x 100 Ohm • Low Insertion Loss • Input to Output DC Isolation • Surface Mountable • Tape & Reel • Non-conductive Surface • RoHS Compliant 	Frequency	3400		3800	MHz
	Unbalanced Port Impedance		50		Ω
	Balanced Port Impedance		200		Ω
	Return Loss	11	15		dB
	Insertion Loss*		0.7	1.0	dB
	Amplitude Balance		0.1	0.6	dB
	Phase Balance		4	10	Degrees
	CMRR		29		dB
	Power Handling @85C			2	Watts
	Power Handling @105C			1.2	Watts
	Operating Temperature	-55		+105	°C

* Insertion Loss stated at room temperature (Insertion Loss is approximately 0.1 dB higher at +85 °C)

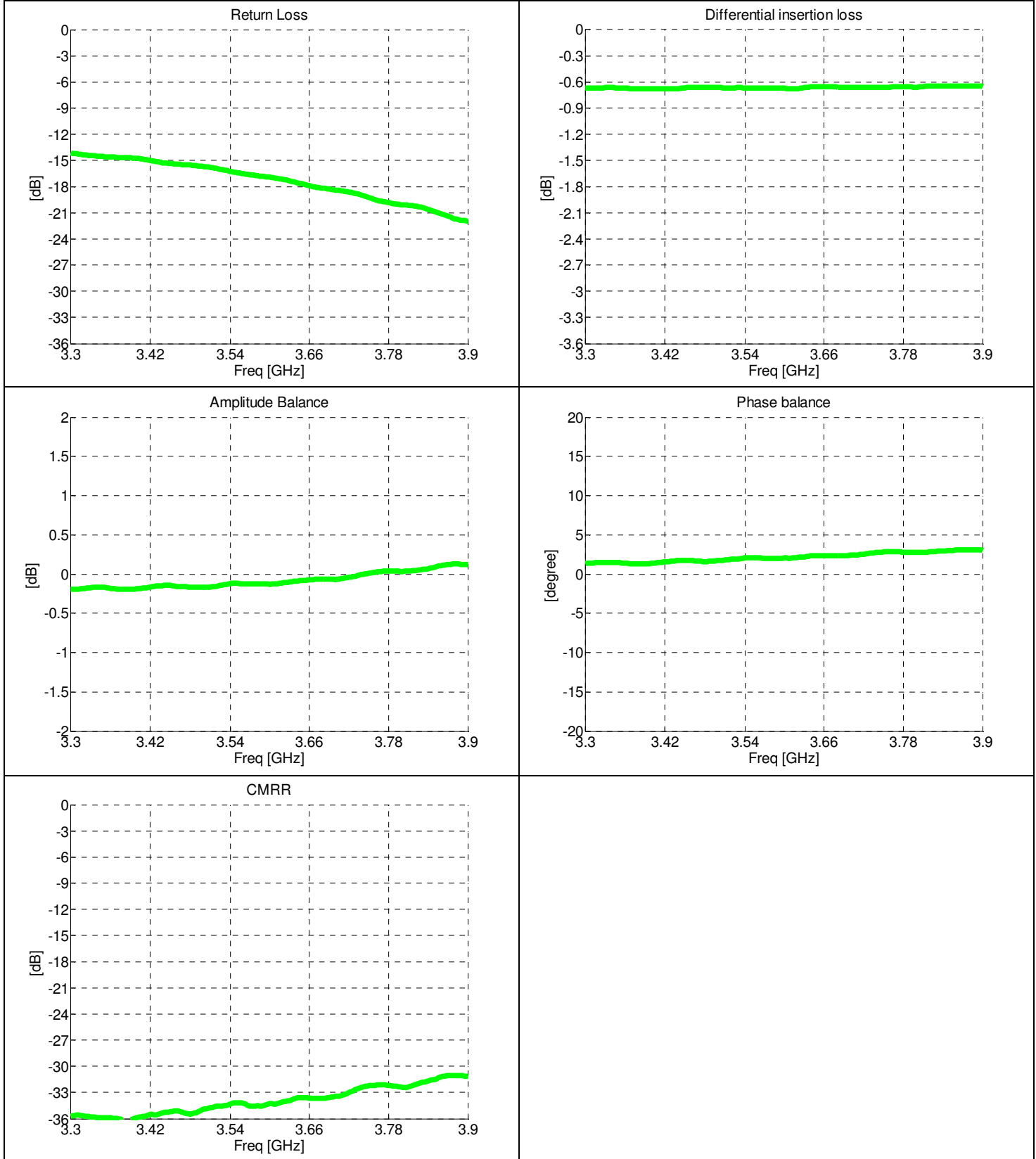
Outline Drawing



Typical Broadband Performance: 10 MHz to 8.01GHz



Typical Performance: 3300 MHz to 3900 MHz



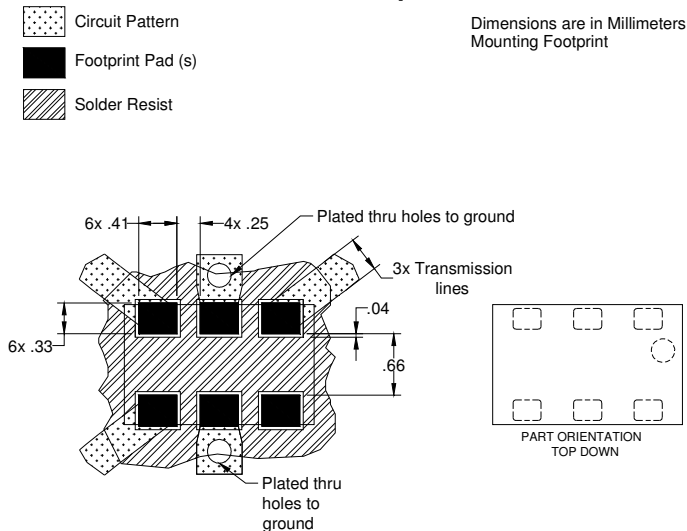
Mounting Configuration:

In order for Xinger surface mount components to work optimally, the proper impedance transmission lines must be used to connect to the RF ports. If this condition is not satisfied, insertion loss, Isolation and VSWR may not meet published specifications.

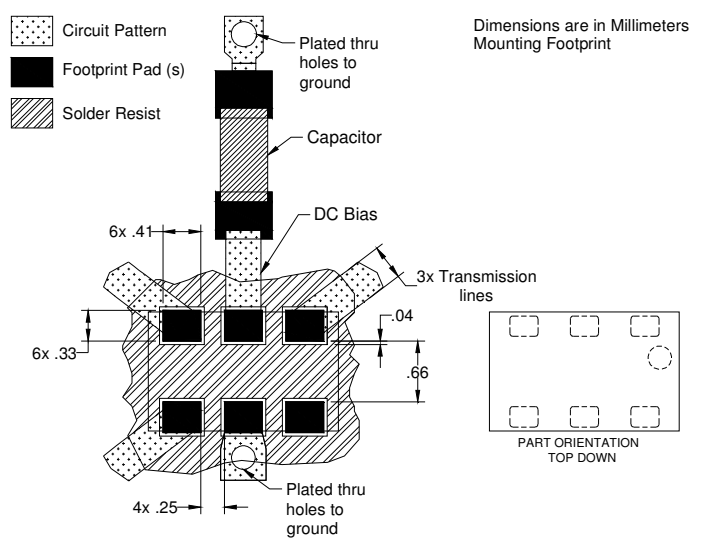
All of the Xinger components are constructed from organic PTFE based composites which possess excellent electrical and mechanical stability. Xinger components are compliant to a variety of ROHS and Green standards and ready for Pb-free soldering processes. Pads are Gold plated with a Nickel barrier.

An example of the PCB footprint used in the testing of these parts is shown below. In specific designs, the transmission line widths need to be adjusted to the unique dielectric coefficients and thicknesses as well as varying pick and place equipment tolerances.

No Bias Footprint



DC Bias Footprint



Packaging and Ordering Information

Parts are available in reel and are packaged per EIA 481-D. Parts are oriented in tape and reel as shown below. Minimum order quantities are 4000 per reel.

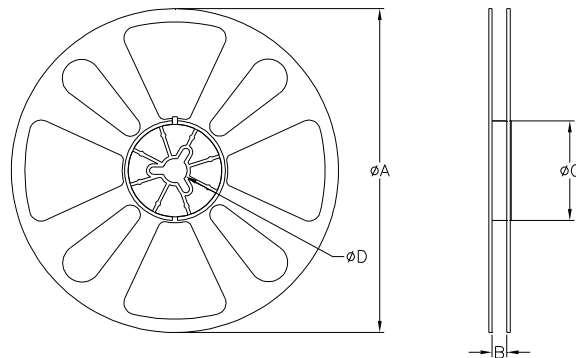
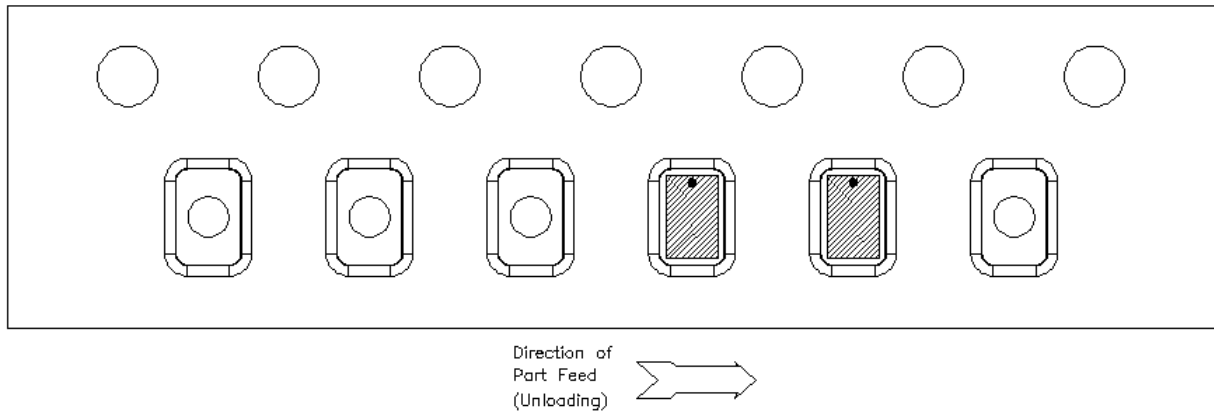


TABLE 1		
QUANTITY/REEL	REEL DIMENSIONS mm	
4000	ϕA	177.80
	B	8.00
	ϕC	50.80
	ϕD	13.00